

Coilmaster



SPECIFICATION APPROVAL

CUSTOMER	:	Devetech
PRODUCT	:	MI2012-331-2A-LF
		Pb-free
CODE NO.	:	C01420025
CUS. CODE	:	
SPEC.NO.	:	C-1420-025(00)
DATE	:	4-Dec-06
CU	J S T	ΓOMER APPROVAL

Coilmaster Electronics Co., Ltd.

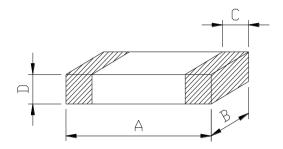
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PREPARED BY	APPROVED BY	AUTHORIZED BY
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PRODUCT	MI2012-331-2A-LF	COIL	DATE	2006/12/4	
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CONFIGURATION & DIMENSIONS:



 $\begin{array}{cccccc} A & \vdots & 2.0 {\pm} 0.2 & & m/m \\ B & \vdots & 1.25 {\pm} 0.2 & & m/m \\ C & \vdots & 0.2 {\sim} 0.8 & & m/m \\ D & \vdots & 0.9 {\pm} 0.2 & & m/m \end{array}$

ELECTRICAL CHARACTERISTIC:

IIMPEDANCE (Ω) AT 100 MHz 500mV : 330 \pm 25% DC RESISTANCE(Ω) : 0.09 Max. RATED CURRENT (mA) : 2000 Max.

STANDARD ATMOSPHERIC CONDITIONS

Unless otherwise specified the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature : $20\pm15^{\circ}$ C Relative humidity : $65\pm20\%$

If there may be any doubt on the results, measurements shall be made within

the following limits:

Ambient temperature : $25\pm5^{\circ}$ C Relative humidity : $75\pm10\%$

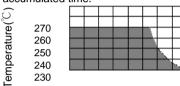
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6) Reflow soldering conditions

 Pre—heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.

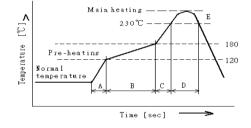
Unenough pre—heating may cause cracks on the ferrite, resulting in the deterioration of product quality.

Products should be soldered within the following allowable range indicated by the slanted line.
 The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.



0 10 20 30 40 50 60 70

Temperature Profile



Α	Slope of temp. rise	1 to 5	°C/sec
В	Heat time	50 to 150	sec
Ь	Heat temperature	120 to 180	$^{\circ}\!\mathbb{C}$
С	Slope of temp. rise	1 to 5	°C/sec
D	Time over 230°C	90~120	sec
Е	Peak temperature	255~260	$^{\circ}\!\mathbb{C}$
	Peak hold time	10 max.	sec
	*No. of mounting	3	times

(Melting area of solder)

6-1 Reworking with soldering iron

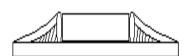
У	with soldering hon	
	Preheating	150℃, Iminute
	Tip temperature	280°C max
	Soldering time	3seconds max.
	Soldering iron output	30w max.
Ī	End of soldering iron	∮ 3mm max.

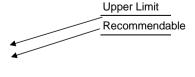
• Reworking should be limited to only one time.

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

6-2 Solder Volume

Solder shall be used not to be exceed the upper limits as shown below.





Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

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7 EQUIPMENT

7-1 IMPEDANCE

Impedance shall be measured with HP-4286A impedance analyzer or equivalent system

7-2 DC RESISTANCE

DC resistance shall be measured using HP 4338 digital mili – ohm meter with 4 terminal method.

8.MECHANICAL CHARACTERISTICS

Without deformation cases	Solder chip on PCB and applied 10N
impedance shall be satisfied ± 30%	(1.02Kgf) for 10 sec
DC resistance shall be satisfied.	CHIP BEAD
	Cities Score IPCS
Without deformation cases,	After soldering a chip to a test substrate,
impedance shall be satisfied ± 30%	bend the substrate by 3mm hold for 10s
DC resistance shall be satisfied.	and then return.
	Soldering shall be done in accordance
	with the recommended PC board pattern
	and reflow soldering.
	unit:mm 45 45 45 100
No visible damage	Solder Temp. : 265±3℃
Electrical characteristics and mechanical characteristics shall be satisfied.	Immersion time : 6±1 sec
	Preheating : 100°C to 150°C, 1 minute.
	Measurement to be made after keeping at room temp fo 24±2 hrs.
	Solder : Sn-3Ag-0.5Cu
95% min. coverage of all	Solder temp. : $240\pm5^{\circ}$ C
metabolised area	Immersion time : 3±1 sec
	Solder : Sn-3Ag-0.5Cu
_	impedance shall be satisfied ± 30% DC resistance shall be satisfied. Without deformation cases, impedance shall be satisfied ± 30% DC resistance shall be satisfied. No visible damage Electrical characteristics and mechanical characteristics shall be satisfied.

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9. RELIABILITY AND TEST CONDITIONS

9-1 HIGH TEMPERATURE RESISTANCE

- a. Performance specification
- 1.Appearance: no mechanical damage
- 2.Impedance shall be with ±30% of the initial value
- 3. DC resistance shall be satisfied
- b.Test condition
- 1.Temperature125°C±2°C
- 2.Applied current : Rated current(maximum value)
- 3.Testing time: 96±4hrs
- 4. Measurement: After placing at room ambient temperature for 1 hours minimum

9-2 HUMIDITY RESISTANCE

- a.Performance specification
- 1.Appearance: no mechanical damage
- 2.Impedance:within ±30% of initial value
- 3.DC resistance shall be satisfied
- b.Test condition
- 1.Humidity: 90 to 95% RH
- 2.Temperature : 60±2°C
- 3.Applied current: Rated current (maximum value)
- 4.Testing tine: 500±4hours
- 5.Measurement: After placing at room ambient temperature for 1 hours minimum

9-3 TEMPERATURE CYCLE

- a.Performance specification
- 1.Appearance: no mechanical damage
- 2.Impedance:within ±30% of initial value
- 3. DC resistance shall be satisfied
- b.Test condition
- 2.Cycle: 100 cycles
- 3. Measurement: After placing for 1 hours minimum at room ambient temperature
- 4. step1. -55°C temp±3°C 30±3 minutes
 - step2. Standard atmospheric conditions 5s or less
 - step3. +125°C temp±2°C 30±3 minutes
 - step4. Standard atmospheric conditions 5s or less

9-4 LOW TEMPERATURE STORAGE LIFE TEST

- a.Performance specification
- 1.Appearance: no mechanical damage
- 2.Impedance shall be with ±30% of the initial value
- 3. DC resistance shall be satisfied
- b.Test condition
- 1.Temperature -55°C ±2°C
- 2.Testing time: 1008±12hours
- 3. Measurement: After placing for 24 hours minimum at room ambient temperature

PRODUCT	MI2012-331-2A-I	.F	CC)IL		I	DATE	200	6/12/4	
SPEC.NO.	C-1420-025(00	SI	SPECIFICATION			CODE NO.		C01	C01420025	
EMBOSSED C	CARRIER TAPE PA	CKAGIN	G							
1 DIM	IENSIONS									
	Ţ2	PI	DI	↑		Unreel	ing directior	→ 1 →		
A0	B0 W	F	Е	P1	P2	P0	D0	Т	T2	
0.9 ±0.1	1.9 8.0 ±0.1 ±0.2	3.5 ±0.05	1.75 ±0.1	4.0	2.00	4.0	1.5 ±0.1	0.2	1.00	
	±0.1 ±0.2 ADER AND TRAILER T		±0.1	±0.1	±0.05	±0.1	±0.1	±0.05	±0.1	
	End Trailer 110mm of moze H. W	Compo		ompar time		Start				
3 DIR	ECTION THE DIRECTIO	N SHALL I	F-4				PE ing direction	<u>`</u>		

COILMASTER ELECTRONICS CO., LTD.

UNIT:mm

A 178
±2.0

N 50
MIN

W1 10
±1.5

20 MAX

4 REELS

PACKING QTY.

4,000 PCS REEL

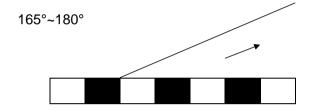
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10-5 PULLING STRENGTH OF TAPES

Carrier tape	(1kgf or more)
Cover tape	(0.5kgf or more)

10-6 PEELING STRENGTH OF COVER TAPE

	Cover tape	(20g~120g)
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Test condition

1) peel angle: 165°~180° vs carrier tape

2) peel speed: 300mm/min

11.PACKAGING

1) Tape & Reel packaging in composite specification 6/8

2) Reel and a bag of desiccant shall be packed in Nylon or plastic bag

3) Maximum of 5 bags shall be packaged in a inner box

4) Maximum of 6 inner box shall be packaged in a outer box

12.Reel Label

Producing the goods label needs to indicate (1) Pb Free (2) RoHS Compliant

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12. STORAGE

- 12-1The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40°C or less and 70% RH or less.
- 12-2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 12-3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun light.
- 12-4 Minimum packages, such as polyvinyl heat—seal packages shall not be opened until just before they are used.If opened, use the reels as soon as possible.
- 12-5 Solderability specified in composite specification 4/8 shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 12-1 & 12-2.

For those parts which passed more than 6 months shall be checked solderability before it is used.

COILMASTER ELECTRONICS CO., LTD.